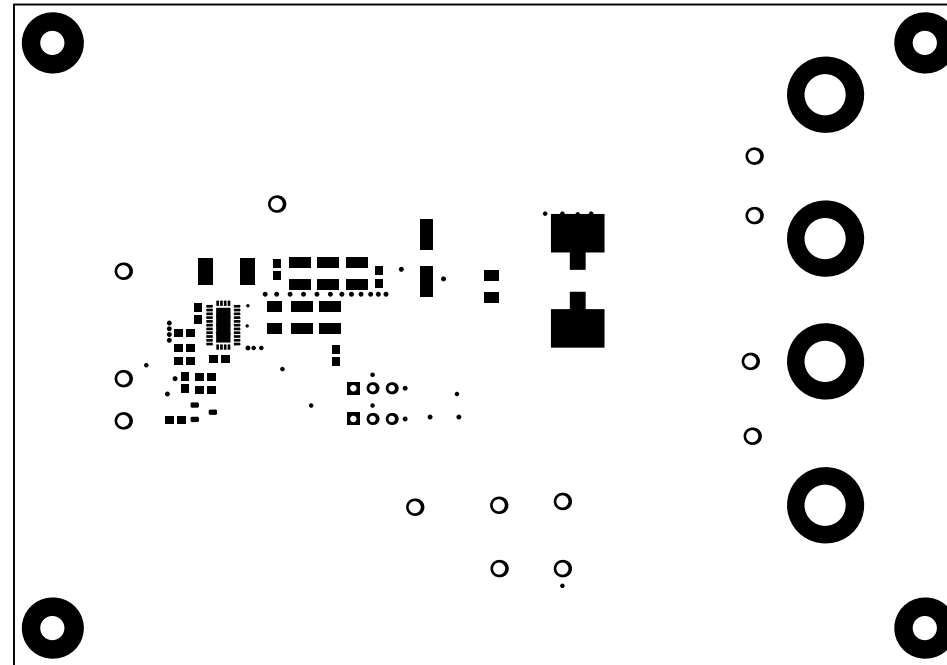
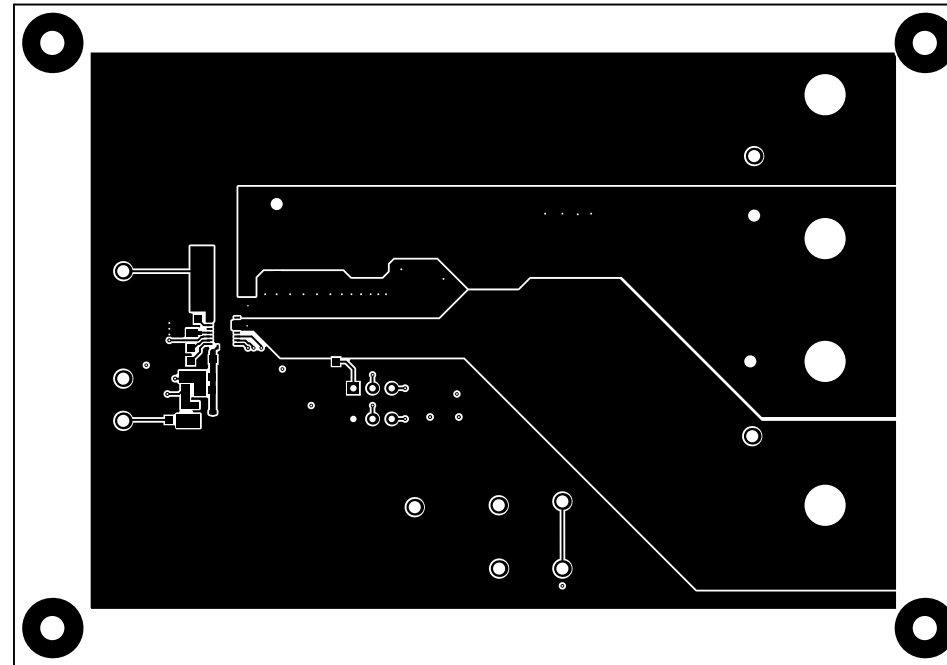


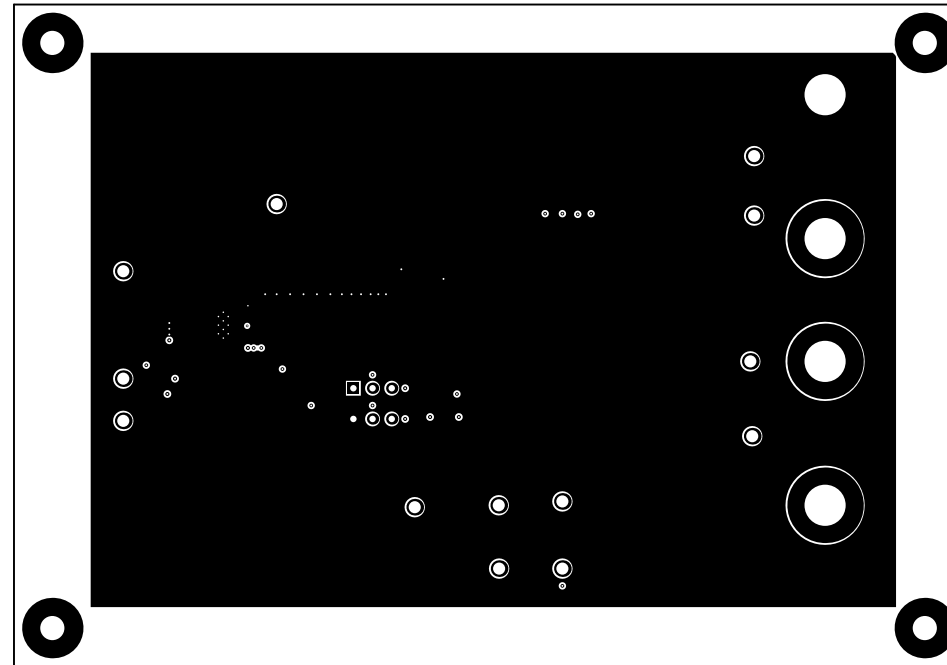
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15026	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 16.02.2018 12:23:24	TEXAS INSTRUMENTS	



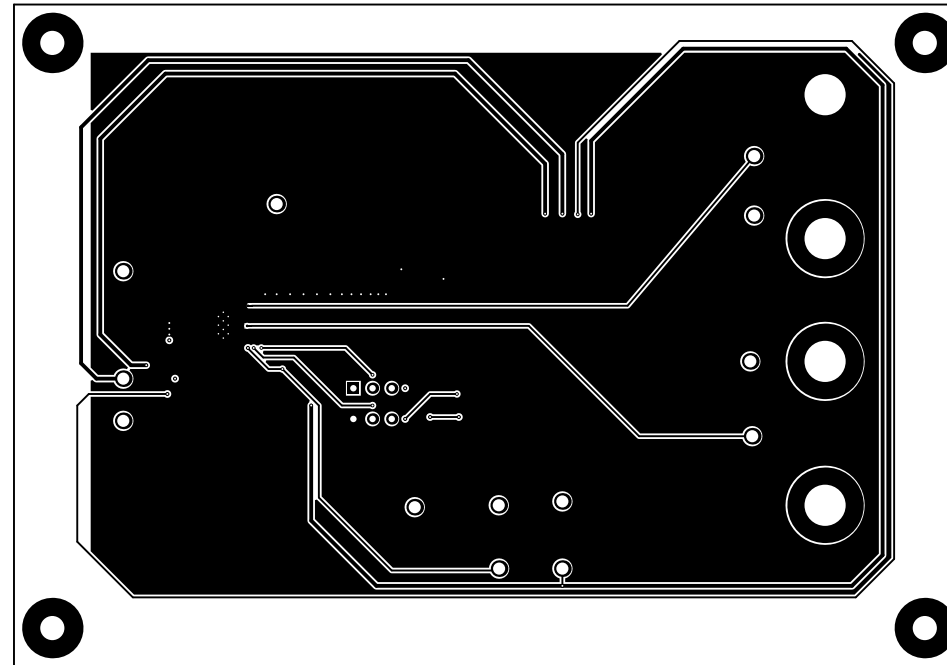
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15026	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 16.02.2018 12:23:25	TEXAS INSTRUMENTS	



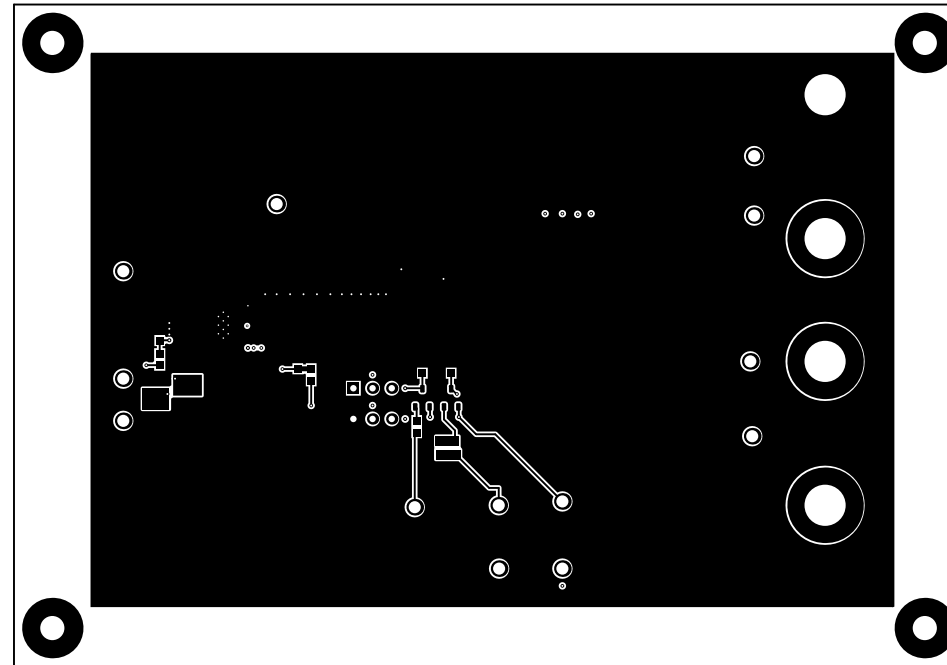
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15026	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 16.02.2018 12:23:26	TEXAS INSTRUMENTS	



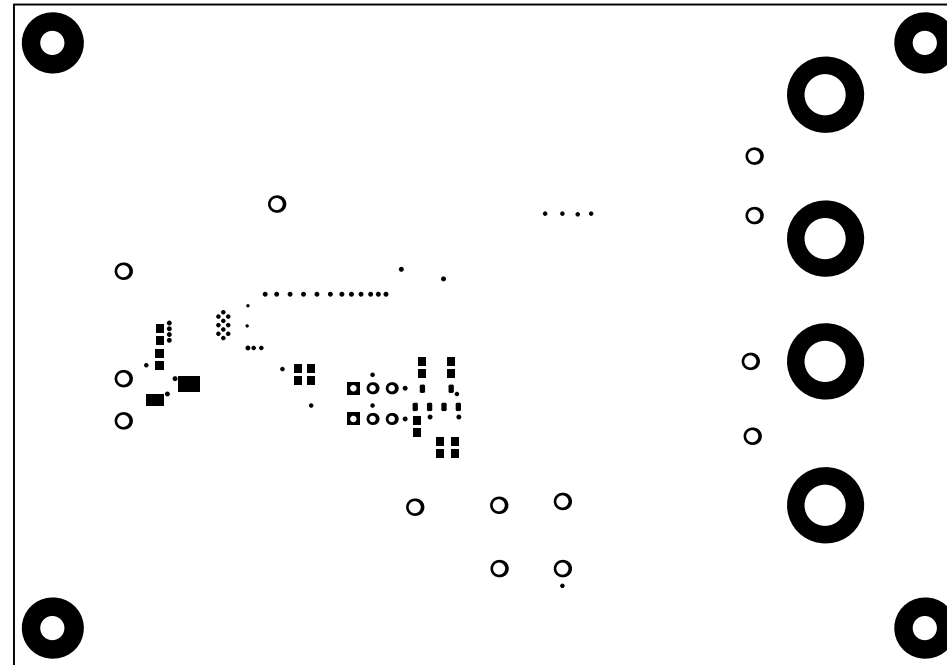
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15026	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 1	GENERATED : 16.02.2018 12:23:27		TEXAS INSTRUMENTS



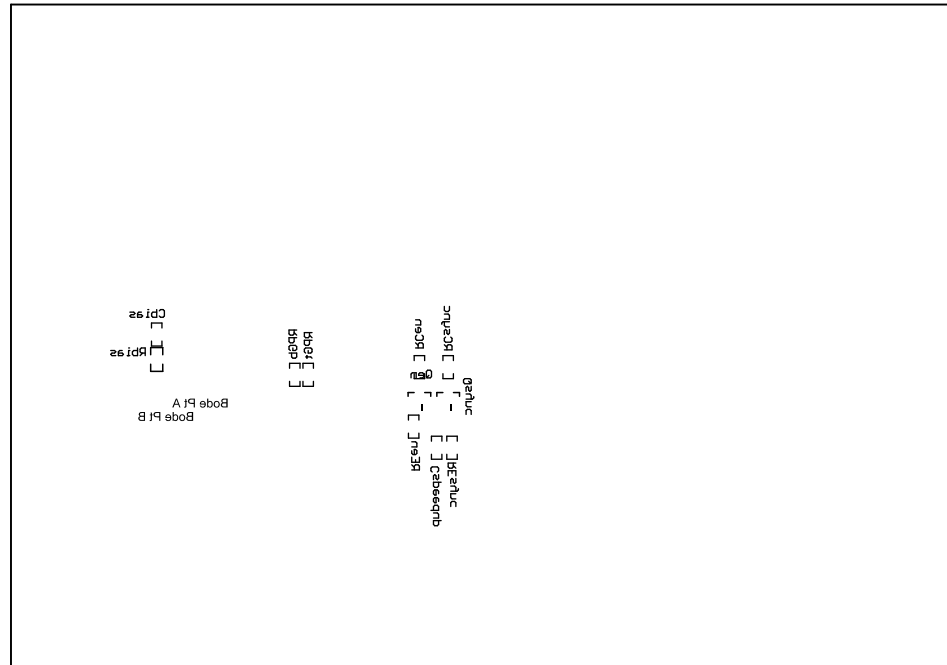
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15026	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 2	GENERATED : 16.02.2018 12:23:27		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15026	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 16.02.2018 12:23:28	TEXAS INSTRUMENTS	

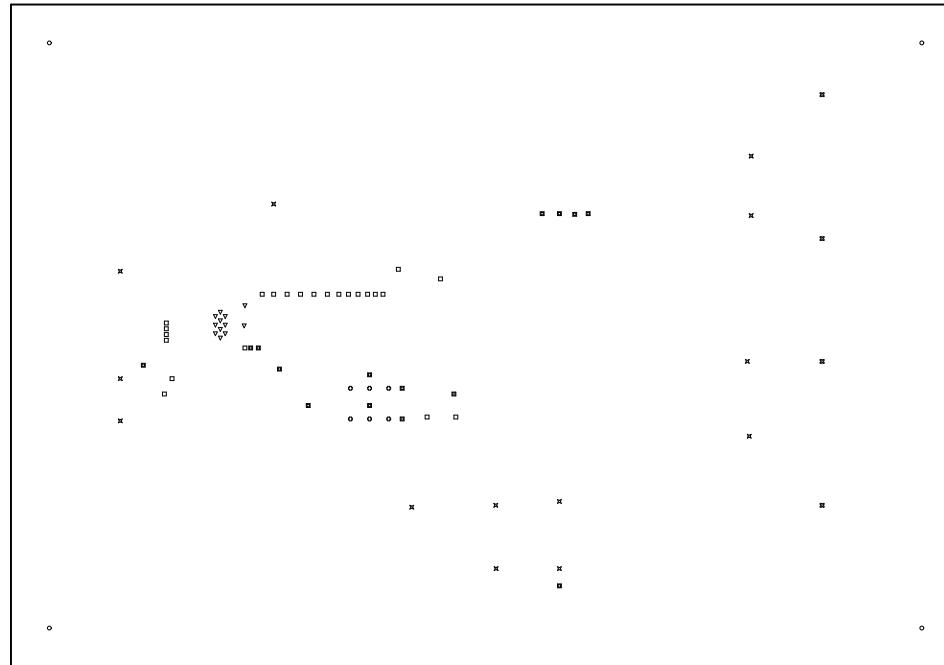


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15026	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 16.02.2018 12:23:29	TEXAS INSTRUMENTS	



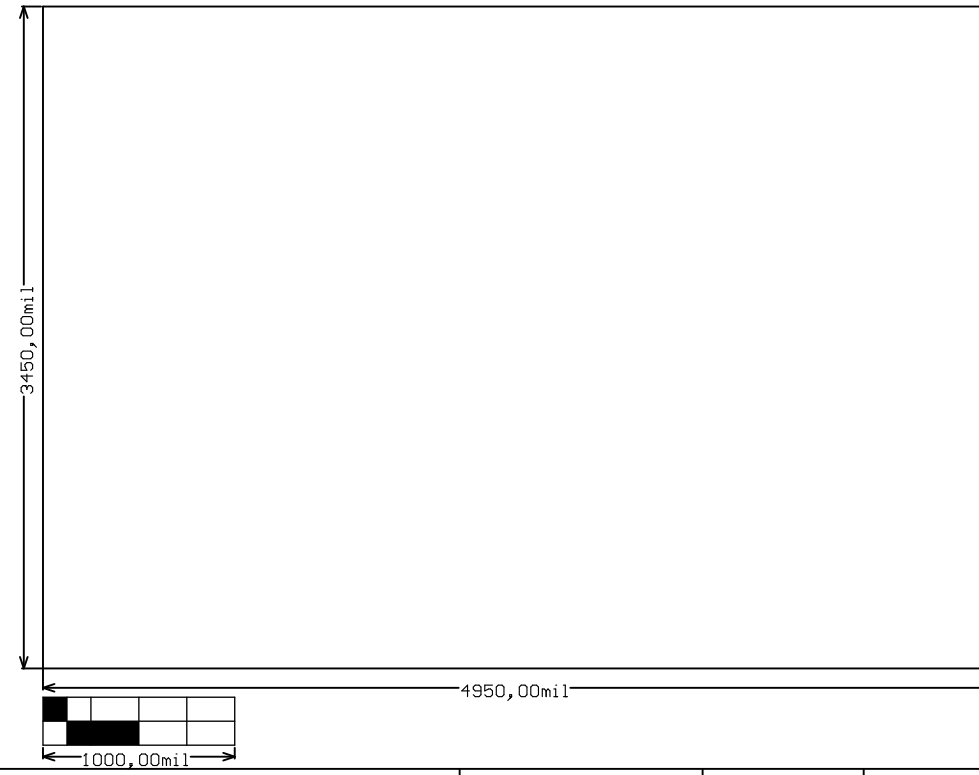
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15026	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 16.02.2018 12:23:30	TEXAS INSTRUMENTS	





Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
▽	12	7,87mil (0,200mm)	PTH	Round	Top Layer - Bottom Layer	
■	15	9,84mil (0,250mm)	PTH	Round	Top Layer - Bottom Layer	
□	23	10,00mil (0,254mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	6	33,46mil (0,850mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	13	63,00mil (1,600mm)	PTH	Round	Top Layer - Bottom Layer	
○	4	125,98mil (3,200mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	4	214,57mil (5,450mm)	PTH	Round	Top Layer - Bottom Layer	
	77 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15026	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 16.02.2018 12:23:31		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15026	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 16.02.2018 12:23:32	TEXAS INSTRUMENTS	

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